

Resource Summary Report

Generated by T1D on Jul 31, 2026

Horiba: GR-300 Series Wafer Back Side Cooling System

RRID:SCR_020075

Type: Tool

Proper Citation

Horiba: GR-300 Series Wafer Back Side Cooling System (RRID:SCR_020075)

Resource Information

URL: https://www.horiba.com/en_en/products/detail/action/show/Product/gr-300-series-713/

Proper Citation: Horiba: GR-300 Series Wafer Back Side Cooling System (RRID:SCR_020075)

Description: Can control gases used to cool back side of wafers that are fixed in position by electrostatic chuck system.

Resource Type: instrument resource

Keywords: Horiba, Wafer Back Side Cooling System, Instrument, Resource Equipment, Equipment, USEDit,

Availability: Commercially available

Resource Name: Horiba: GR-300 Series Wafer Back Side Cooling System

Resource ID: SCR_020075

Alternate IDs: Model_Number_GR_300

Record Creation Time: 20220129T080348+0000

Record Last Update: 20260725T190923+0000

Ratings and Alerts

No rating or validation information has been found for Horiba: GR-300 Series Wafer Back Side Cooling System.

No alerts have been found for Horiba: GR-300 Series Wafer Back Side Cooling System.

Data and Source Information

Source: [SciCrunch Registry](#)

Usage and Citation Metrics

We have not found any literature mentions for this resource.